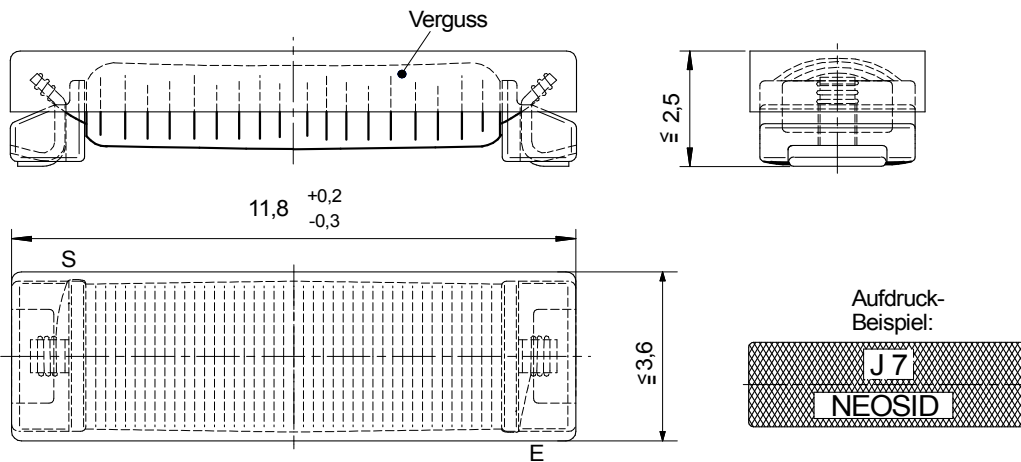


Mikrospule Ms 32 ka / 10,4 mH

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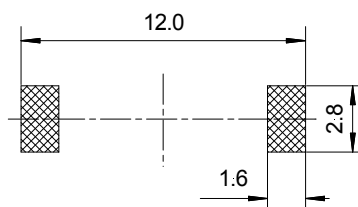
Markierung: Produktionsdatum nach DIN EN 60062 und Neosid.

Einheiten: mm

Schaltung



Lötflächen - Empfehlung



Prüfung: Messger.: L, R = Agilent E 4980 A, f_{res} = Agilent E5061B, äquivalent zul.

L [mH] bei U=0,1V	± %	$R_{dc} \leq$ [Ω]	$f_{res} \geq$ [kHz]	f_L [kHz]	Bemerkung
10,4	10	80	370	25	

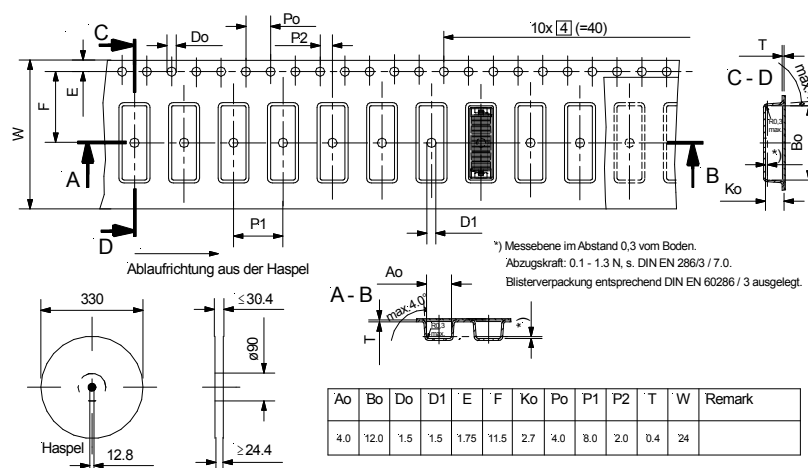
Bemerkung:

Betriebstemperaturbereich: -40° C – +125° C

max. Löttemperatur: 260° C, 10 Sek.

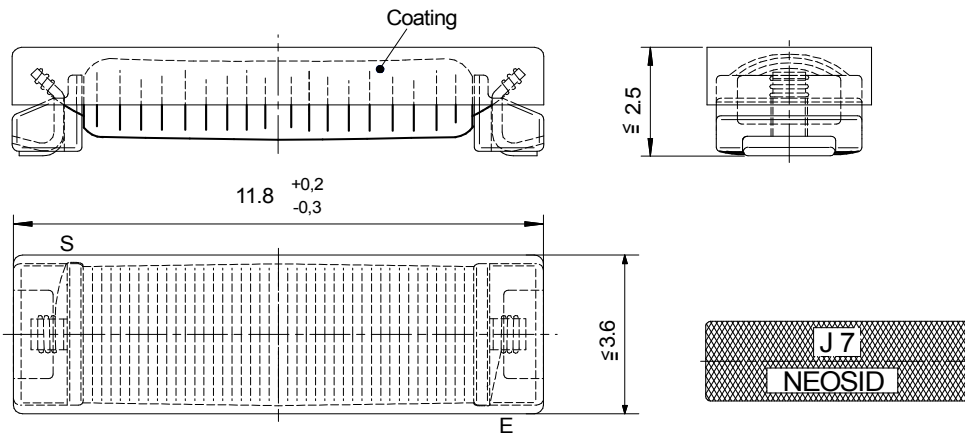
Lager- und Transportbedingung (im Blistergurt): +10° ... +40° C;
≤70% rel. Luftfeuchtigkeit dunkel lagern bzw. transportieren.

Verpackung: Blisterverpack.: 79 9420 10
VPE = 3000 Stk. / Rolle



SMD Inductor Ms 32 ka / 10.4 mH

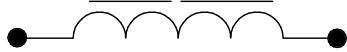
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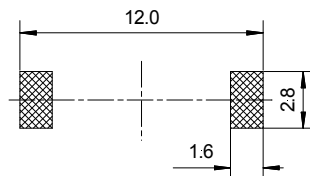
Marking: Production date acc. DIN EN 60062 and Neosid.

Dimensions: mm

Circuit



Solder areas - Recommendation



Solderable acc. IPC/JEDEC J-STD-020-D

Testing:

Measured with: L, R_{DC} = Agilent E 4980 A
f_{res} = Agilent E5061B

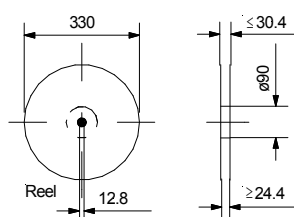
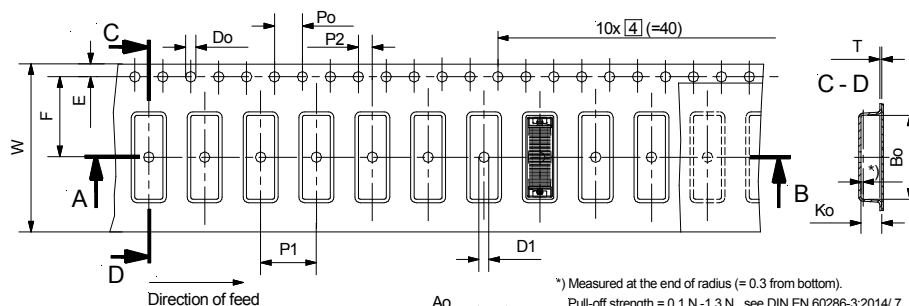
L [mH] at U=0.1V	± %	R _{dc} ≤ [Ω]	f _{res} ≥ [kHz]	f _L [kHz]	Remark
10.4	10	80	370	25	

Operating temperature range: -40°C – + 125°C.

Max. soldering temperature: 260°C, 10 sec.

Storage- and transport conditions (in blisterpack): +10°...+40°C ;
≤70% rel. humidity, dark storage and transport conditions.

Blisterpackag.: 79 9420 10
Unit = 3000 pcs / reel



Ao	Bo	Do	D1	E	F	Ko	Po	P1	P2	T	W
4.0	12.0	1.5	1.5	1.75	11.5	2.7	4.0	8.0	2.0	0.4	24

Blister pack according to DIN EN 60286/3:2014 designed.

Alle Angaben ohne Gewähr. Irrtümer und Änderungen vorbehalten. No responsibility is taken for the correctness. Errors and changings reserved.